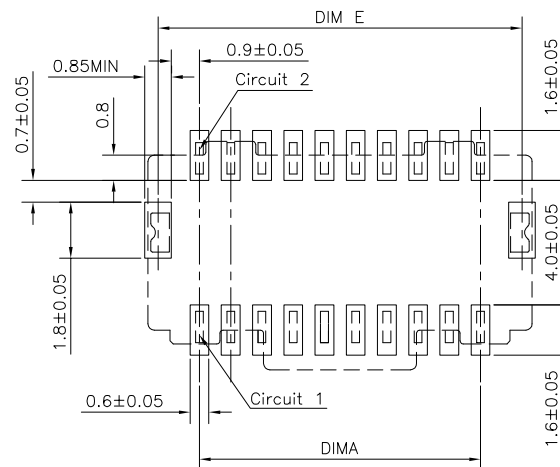
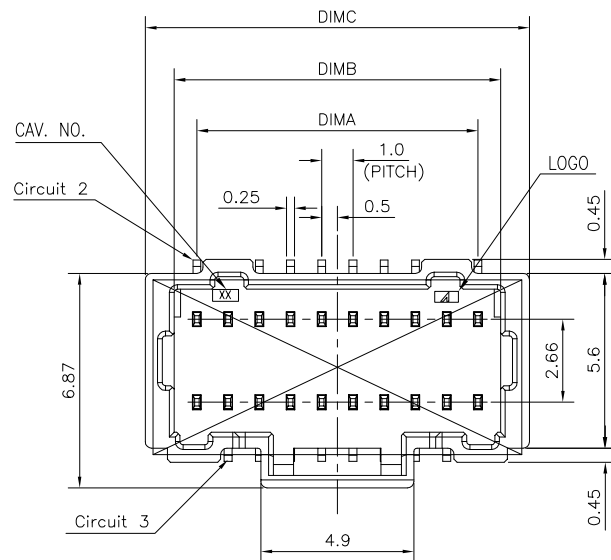
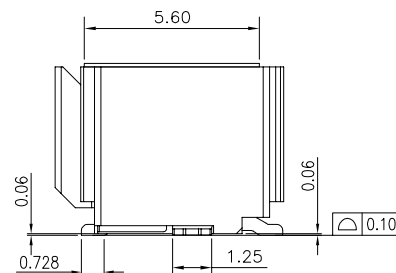
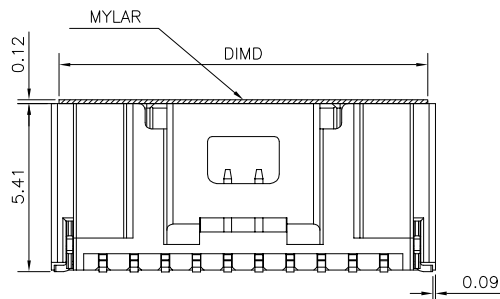
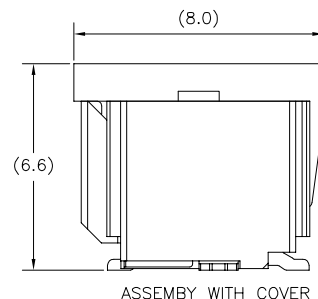




RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05



NOTES:

1. MATERIAL:

- 1.1 HOUSING: THERMOPLASTIC, HIGH TEMP., UL94V-0
- 1.2 COVER: THERMOPLASTIC, HIGH TEMP., UL94V-0
- 1.3 CONTACT: COPPER ALLOY
- 1.4 FITTING NAIL: COPPER ALLOY

2. FINISH:

- 2.1 CONTACT: 50u" MIN. NICKEL UNDERPLATING OVERALL.
1: GOLD FLASH ON CONTACT AND SOLDER AREA
4: 4u" GOLD ON CONTACT AND SOLDER AREA
C: 15u" GOLD ON CONTACT AND GOLD FLASH ON SOLDER AREA
D: 30u" GOLD ON CONTACT AND GOLD FLASH ON SOLDER AREA
- 2.2 FITTING NAIL: 50u" MIN. NICKEL UNDERPLATING OVERALL.
N: 80u" MIN. MATTE TIN PLATING

3. REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.

4. SPEC. PLS. REFER TO PS-51347-XXXX-XXX

5. PACKAGE PLS. REFER TO 51347-XXXX-XX-TRP.

6. PART NUMBER

52255-XXX X X-XXX
CKTS

XXX	Color	PACKING
001	NATURAL	51347-XXXCR-00
004	BLACK	52255-XXXCR-05
003	BLACK	51347-XXXCR-01
005	BLACK	52255-XXXCR-03

PACKING

0: TAPE & REEL

4: TAPE & REEL WITH MYLAR

7: TAPE & REEL WITH COVER

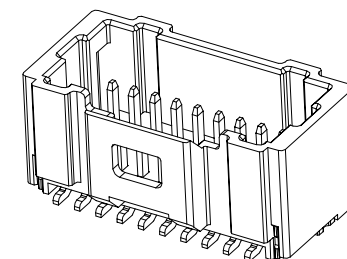
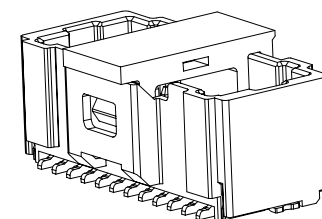
PLATING

1: GOLD FLASH PLATING

4: 4u" GOLD ON CONTACT AREA

C: 15u" GOLD ON CONTACT AREA

D: 30u" GOLD ON CONTACT AREA



CKTS	DIM A	DIM B	DIM C	Mylar Size	DIM E
20.00	9.00	10.45	12.30	11.80	11.65
30.00	14.00	15.45	17.30	13.80	16.65
40.00	19.00	20.45	22.30	21.80	21.65
50.00	24.00	25.45	27.30	26.80	26.65

QUALITY SYMBOLS MAJOR CRITICAL GENERAL TOLERANCES (UNLESS SPECIFIED) X. ± 0.5 .X ± 0.25 .XX ± 0.15 .XXX ± 0.1 ANGLES $\pm 2^\circ$	DRAWN BY Guo, Fei	DATE 24'/07/23	ACES ELECTRONICS 1.0mm pitch WTB Conn.SMT D/R S/T Type		
	CHECKED BY Xu, ZhiYong	DATE 24'/07/23			
	APPROVED BY Xu, ZhiYong	DATE 24'/07/23	UNITS mm	SIZE A4	DWG NO. N/A
	SCALE 1 : 1	SHEET NO. 1 OF 1	REV E	PART NO. 52255-XXXXX-XXX	